

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
18 July 2002 (18.07.2002)

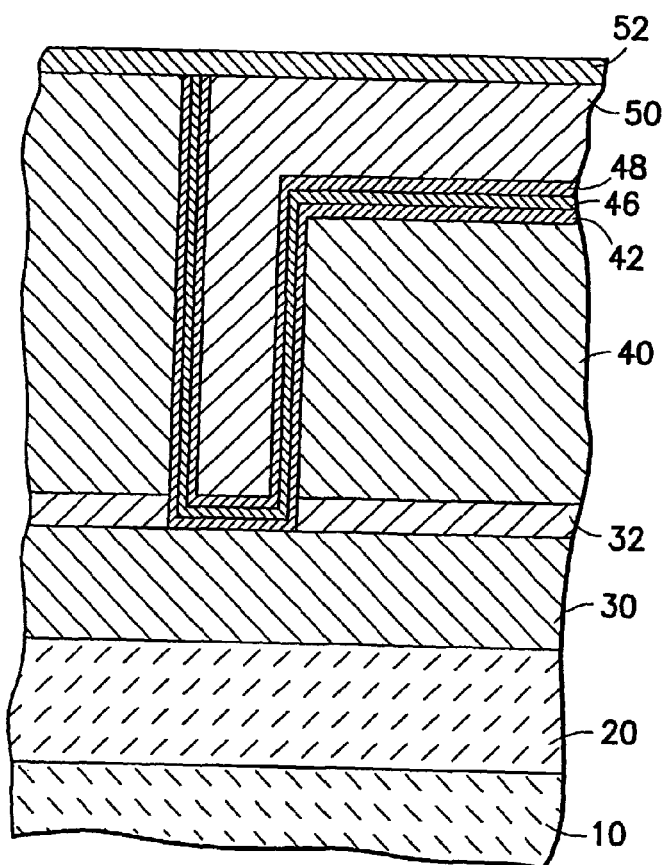
PCT

(10) International Publication Number
WO 02/056337 A1

- (51) International Patent Classification⁷: **H01K 3/10**
- (21) International Application Number: PCT/US01/47815
- (22) International Filing Date:
13 December 2001 (13.12.2001)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
09/759,017 11 January 2001 (11.01.2001) US
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- (81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,

[Continued on next page]

(54) Title: CHROMIUM ADHESION LAYER FOR COPPER VIAS IN LOW-K TECHNOLOGY



(57) Abstract: In integrated circuits having copper interconnect (30, 50) and low-k interlayer dielectrics (40), a problem of open circuits after heat treatment was discovered and solved by the use of a first liner layer of Cr (42), followed by a conformal liner layer of CVD TiN (46), followed in turn by a final liner layer of Ta or TaN (48), thus improving adhesion between the via (50) and the underlying copper layer (30) while maintaining low resistance.

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MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK,
SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.

Published:

— with international search report

(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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